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Details	
Product Status	Active
Number of LABs/CLBs	29080
Number of Logic Elements/Cells	77000
Total RAM Bits	5001216
Number of I/O	240
Number of Gates	-
Voltage - Supply	1.07V ~ 1.13V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	484-BGA
Supplier Device Package	484-FBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5cgtfd5c5f23c7n

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Cyclone V Device Overview

The Cyclone® V devices are designed to simultaneously accommodate the shrinking power consumption, cost, and time-to-market requirements; and the increasing bandwidth requirements for high-volume and cost-sensitive applications.

Enhanced with integrated transceivers and hard memory controllers, the Cyclone V devices are suitable for applications in the industrial, wireless and wireline, military, and automotive markets.

Related Information

Cyclone V Device Handbook: Known Issues

Lists the planned updates to the Cyclone V Device Handbook chapters.

Key Advantages of Cyclone V Devices

Table 1. Key Advantages of the Cyclone V Device Family

Advantage	Supporting Feature
Lower power consumption	Built on TSMC's 28 nm low-power (28LP) process technology and includes an abundance of hard intellectual property (IP) blocks Up to 40% lower power consumption than the previous generation device
Improved logic integration and differentiation capabilities	8-input adaptive logic module (ALM) Up to 13.59 megabits (Mb) of embedded memory Variable-precision digital signal processing (DSP) blocks
Increased bandwidth capacity	3.125 gigabits per second (Gbps) and 6.144 Gbps transceivers Hard memory controllers
Hard processor system (HPS) with integrated Arm* Cortex*-A9 MPCore* processor	 Tight integration of a dual-core Arm Cortex-A9 MPCore processor, hard IP, and an FPGA in a single Cyclone V system-on-a-chip (SoC) Supports over 128 Gbps peak bandwidth with integrated data coherency between the processor and the FPGA fabric
Lowest system cost	Requires only two core voltages to operate Available in low-cost wirebond packaging Includes innovative features such as Configuration via Protocol (CvP) and partial reconfiguration



Summary of Cyclone V Features

Summary of Features for Cyclone V Devices Table 2.

Feature		Description				
Technology	TSMC's 28-nm low-p 1.1 V core voltage	ower (28LP) process technology				
Packaging	Multiple device densi different device densi	Multiple device densities with compatible package footprints for seamless migration between different device densities				
High-performance FPGA fabric	Enhanced 8-input ALM v	vith four registers				
Internal memory blocks	•	(b) memory blocks with soft error correction code (ECC) block (MLAB)—640-bit distributed LUTRAM where you can use up to 25% memory				
Embedded Hard IP blocks	 Variable-precision DSP Native support for up to three signal processing precision le (three 9 x 9, two 18 x 18, or one 27 x 27 multiplier) in the variable-precision DSP block 64-bit accumulator and cascade Embedded internal coefficient memory Preadder/subtractor for improved efficiency 					
	Memory controller DDR3, DDR2, and LPDDR2 with 16 and 32 bit ECC support					
	Embedded transceiver I/O	PCI Express* (PCIe*) Gen2 and Gen1 (x1, x2, or x4) hard IP with multifunction support, endpoint, and root port				
Clock networks		ol clock network d peripheral clock networks are not used can be powered down to reduce dynamic power				
Phase-locked loops (PLLs)	Precision clock synth Integer mode and from	esis, clock delay compensation, and zero delay buffering (ZDB) actional mode				
FPGA General-purpose I/Os (GPIOs)	400 MHz/800 Mbps 6 On-chip termination	cond (Mbps) LVDS receiver and 840 Mbps LVDS transmitter external memory interface (OCT) p to 16 mA drive strength				
Low-power high-speed serial interface	 614 Mbps to 6.144 Gbps integrated transceiver speed Transmit pre-emphasis and receiver equalization Dynamic partial reconfiguration of individual channels 					
HPS (Cyclone V SE, SX, and ST devices only)	 Single or dual-core Arm Cortex-A9 MPCore processor-up to 925 MHz maximum frequency with support for symmetric and asymmetric multiprocessing Interface peripherals—10/100/1000 Ethernet media access control (EMAC), USB 2.0 On-The-GO (OTG) controller, quad serial peripheral interface (QSPI) flash controller, NAND flash controller, Secure Digital/MultiMediaCard (SD/MMC) controller, UART, controller area network (CAN), serial peripheral interface (SPI), I²C interface, and up to 85 HPS GPIO interfaces 					
		-general-purpose timers, watchdog timers, direct memory access (DMA) iguration manager, and clock and reset managers ot ROM				
	·	continued				

⁽¹⁾ Contact Intel for availability.



Available Options

Figure 2. Sample Ordering Code and Available Options for Cyclone V GX Devices

The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

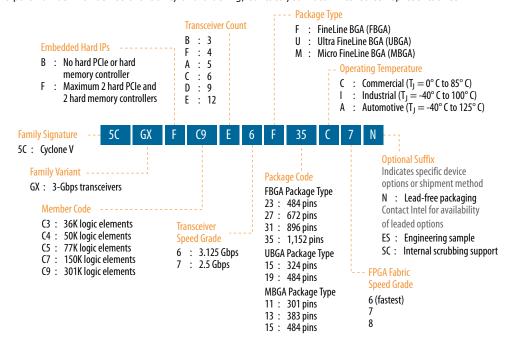


Table 6. Maximum Resource Counts for Cyclone V GX Devices

Reso	urce	Member Code					
		С3	C4	C5	C7	С9	
Logic Elements ((LE) (K)	36	50	77	150	301	
ALM		13,460	18,860	29,080	56,480	113,560	
Register		53,840	75,440	116,320	225,920	454,240	
Memory (Kb)	M10K	1,350	2,500	4,460	6,860	12,200	
	MLAB	182	424	424	836	1,717	
Variable-precision	n DSP Block	57	70	150	156	342	
18 x 18 Multiplie	er	114	140	300	312	684	
PLL		4	6	6	7	8	
3 Gbps Transceiver		3	6	6	9	12	
GPIO ⁽⁴⁾		208	336	336	480	560	
						continued	

⁽⁴⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus® Prime software, the number of user I/Os includes transceiver I/Os.



Available Options

Figure 3. Sample Ordering Code and Available Options for Cyclone V GT Devices

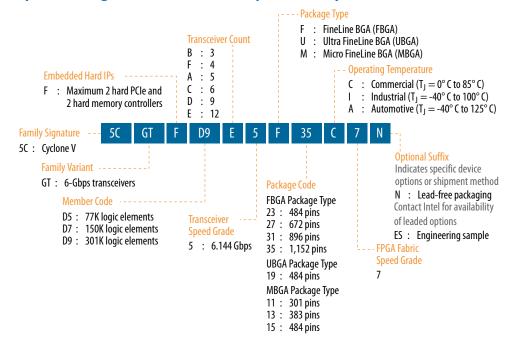


Table 8. Maximum Resource Counts for Cyclone V GT Devices

Resource		Member Code				
		D5	D7	D9		
Logic Elements (LE) (K)	77	301			
ALM		29,080	56,480	113,560		
Register		116,320	225,920 454,240			
Memory (Kb)	M10K	4,460	6,860	12,200		
	MLAB	424	836	1,717		
Variable-precision DS	P Block	150	156	342		
18 x 18 Multiplier		300	312	684		
PLL	L		7	8		
6 Gbps Transceiver		6	9	12		
GPIO ⁽⁵⁾		336	480	560		
LVDS	Transmitter	84	120	140		
	,	•		continued		

⁽⁵⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

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Resource		Member Code				
		D5	D7	D9		
	Receiver	84	140			
PCIe Hard IP Block		2	2	2		
Hard Memory Controller		2	2	2		

Related Information

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices

Provides the number of LVDS channels in each device package.

Package Plan

Table 9. Package Plan for Cyclone V GT Devices

Transceiver counts shown are for transceiver ≤ 5 Gbps . 6 Gbps transceiver channel count support depends on the package and channel usage. For more information about the 6 Gbps transceiver channel count, refer to the Cyclone V Device Handbook Volume 2: Transceivers.

Member Code	M3 (11 i		M383 (13 mm)		M484 (15 mm)		U484 (19 mm)	
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
D5	129	4	175	6	_	_	224	6
D7	_	_	_	_	240	3	240	6
D9	_	_	_	_	_	_	240	5

Member Code	F48 (23 I		F6 (27 I					
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
D5	240	6	336	6	_	_	_	_
D7	240	6	336	9 (6)	480	9 (6)	_	_
D9	224	6	336	9 (6)	480	12 ⁽⁷⁾	560	12 ⁽⁷⁾

Related Information

6.144-Gbps Support Capability in Cyclone V GT Devices, Cyclone V Device Handbook Volume 2: Transceivers

Provides more information about 6 Gbps transceiver channel count.

⁽⁶⁾ If you require CPRI (at 6.144 Gbps) and PCIe Gen2 transmit jitter compliance, Intel recommends that you use only up to three full-duplex transceiver channels for CPRI, and up to six full-duplex channels for PCIe Gen2. The CMU channels are not considered full-duplex channels.

⁽⁷⁾ If you require CPRI (at 6.144 Gbps) and PCIe Gen2 transmit jitter compliance, Intel recommends that you use only up to three full-duplex transceiver channels for CPRI, and up to eight full-duplex channels for PCIe Gen2. The CMU channels are not considered full-duplex channels.



Cyclone V SE

This section provides the available options, maximum resource counts, and package plan for the Cyclone V SE devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

Related Information

Product Selector Guide

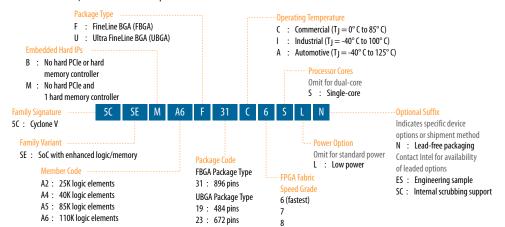
Provides the latest information about Intel products.

Available Options

Figure 4. Sample Ordering Code and Available Options for Cyclone V SE Devices

The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

Cyclone V SE and SX low-power devices (L power option) offer 30% static power reduction for devices with 25K LE and 40K LE, and 20% static power reduction for devices with 85K LE and 110K LE.





Maximum Resources

Table 10. **Maximum Resource Counts for Cyclone V SE Devices**

Res	ource		Member Code					
		A2	A4	A5	A6			
Logic Elements (LE) (K)	25	40	85	110			
ALM		9,430	15,880	32,070	41,910			
Register		37,736	60,376	128,300	166,036			
Memory (Kb)	M10K	1,400	2,700	3,970	5,570			
	MLAB	138	231	480	621			
Variable-precisio	n DSP Block	36	84	87	112			
18 x 18 Multiplie	18 x 18 Multiplier		168	174	224			
FPGA PLL		5	5	6	6			
HPS PLL		3	3	3	3			
FPGA GPIO		145	145	288	288			
HPS I/O		181	181	181	181			
LVDS	Transmitter	32	32	72	72			
	Receiver	37	37	72	72			
FPGA Hard Memo	ory Controller	1	1 1 1		1			
HPS Hard Memor	HPS Hard Memory Controller		1	1	1			
Arm Cortex-A9 M	1PCore Processor	Single- or dual- core	Single- or dual- core	Single- or dual-core	Single- or dual-core			

Related Information

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices Provides the number of LVDS channels in each device package.

Package Plan

Package Plan for Cyclone V SE Devices Table 11.

The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.

Member Code	U484 (19 mm)				F896 (31 mm)	
	FPGA GPIO	HPS I/O	FPGA GPIO	HPS I/O	FPGA GPIO	HPS I/O
A2	66	151	145	181	_	_
A4	66	151	145	181	_	_
A5	66	151	145	181	288	181
A6	66	151	145	181	288	181



Cyclone V SX

This section provides the available options, maximum resource counts, and package plan for the Cyclone V SX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

Related Information

Product Selector Guide

Provides the latest information about Intel products.

Available Options

Figure 5. Sample Ordering Code and Available Options for Cyclone V SX Devices

The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

Cyclone V SE and SX low-power devices (L power option) offer 30% static power reduction for devices with 25K LE and 40K LE, and 20% static power reduction for devices with 85K LE and 110K LE.

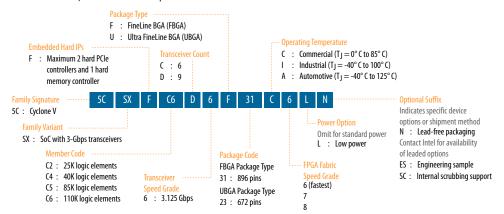


Table 12. Maximum Resource Counts for Cyclone V SX Devices

Resc	ource		Membe	er Code	
		C2	C4	C5	C6
Logic Elements (LE) (K)		25	40	85	110
ALM		9,430	15,880	32,070	41,910
Register	ster		60,376	128,300	166,036
Memory (Kb)	M10K	1,400	2,700	3,970	5,570
	MLAB	138	231	480	621
Variable-precision [DSP Block	36	84	87	112
18 x 18 Multiplier		72	168	174	224
FPGA PLL		5	5	6	6
					continued



Resource		Member Code				
		C2	C4	C5	C6	
HPS PLL		3	3	3	3	
3 Gbps Transceiver		6	6	9	9	
FPGA GPIO (8)		145	145	288	288	
HPS I/O		181	181	181	181	
LVDS	Transmitter	32	32	72	72	
	Receiver	37	37	72	72	
PCIe Hard IP Block		2	2	2 (9)	2 (9)	
FPGA Hard Memory Controller		1	1	1	1	
HPS Hard Memory Controller		1	1	1	1	
Arm Cortex-A9 MP0	Core Processor	Dual-core	Dual-core	Dual-core	Dual-core	

Related Information

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices

Provides the number of LVDS channels in each device package.

Package Plan

Table 13. Package Plan for Cyclone V SX Devices

The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.

Member Code	U672 (23 mm)			F896 (31 mm)		
	FPGA GPIO	HPS I/O	XCVR	FPGA GPIO	HPS I/O	XCVR
C2	145	181	6	_	_	_
C4	145	181	6	_	_	_
C5	145	181	6	288	181	9
C6	145	181	6	288	181	9

Cyclone V ST

This section provides the available options, maximum resource counts, and package plan for the Cyclone V ST devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

⁽⁸⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

^{(9) 1} PCIe Hard IP Block in U672 package.



Related Information

Product Selector Guide

Provides the latest information about Intel products.

Available Options

Figure 6. Sample Ordering Code and Available Options for Cyclone V ST Devices

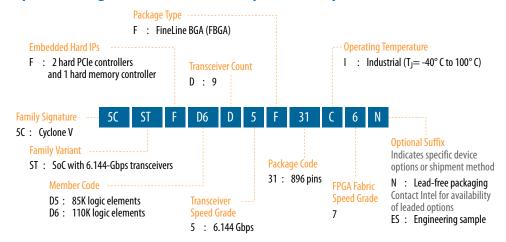


Table 14. Maximum Resource Counts for Cyclone V ST Devices

Reso	ource	Membe	r Code	
		D5	D6	
Logic Elements (LE) (K)		85	110	
ALM		32,070	41,910	
Register		128,300	166,036	
Memory (Kb)	M10K	3,970	5,570	
	MLAB	480	621	
Variable-precision DSP Block		87	112	
18 x 18 Multiplier		174	224	
FPGA PLL		6	6	
HPS PLL		3	3	
6.144 Gbps Transceiver	4 Gbps Transceiver		9	
FPGA GPIO ⁽¹⁰⁾		288	288	
HPS I/O		181	181	
LVDS	Transmitter	72	72	
continued				

⁽¹⁰⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

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Resource		Member Code		
		D5	D6	
Receiver		72	72	
PCIe Hard IP Block		2	2	
FPGA Hard Memory Controller		1	1	
HPS Hard Memory Controller		1	1	
Arm Cortex-A9 MPCore Processor		Dual-core	Dual-core	

Related Information

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices

Provides the number of LVDS channels in each device package.

Package Plan

Table 15. Package Plan for Cyclone V ST Devices

- The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.
- Transceiver counts shown are for transceiver ≤5 Gbps . 6 Gbps transceiver channel count support depends on the package and channel usage. For more information about the 6 Gbps transceiver channel count, refer to the Cyclone V Device Handbook Volume 2: Transceivers.

Member Code	F896 (31 mm)			
	FPGA GPIO	HPS I/O	XCVR	
D5	288	181	9 (11)	
D6	288	181	9 (11)	

Related Information

6.144-Gbps Support Capability in Cyclone V GT Devices, Cyclone V Device Handbook Volume 2: Transceivers

Provides more information about 6 Gbps transceiver channel count.

⁽¹¹⁾ If you require CPRI (at 4.9152 Gbps) and PCIe Gen2 transmit jitter compliance, Intel recommends that you use only up to seven full-duplex transceiver channels for CPRI, and up to six full-duplex channels for PCIe Gen2. The CMU channels are not considered full-duplex channels.



Table 16. Variable-Precision DSP Block Configurations for Cyclone V Devices

Usage Example	Multiplier Size (Bit)	DSP Block Resource
Low precision fixed point for video applications	Three 9 x 9	1
Medium precision fixed point in FIR filters	Two 18 x 18	1
FIR filters and general DSP usage	Two 18 x 18 with accumulate	1
High precision fixed- or floating-point implementations	One 27 x 27 with accumulate	1

You can configure each DSP block during compilation as independent three 9 \times 9, two 18 \times 18, or one 27 \times 27 multipliers. With a dedicated 64 bit cascade bus, you can cascade multiple variable-precision DSP blocks to implement even higher precision DSP functions efficiently.

Table 17. Number of Multipliers in Cyclone V Devices

The table lists the variable-precision DSP resources by bit precision for each Cyclone V device.

Variant Member Code		Variable- precision DSP Block		dent Input and plications Ope		18 x 18 Multiplier Adder Mode	18 x 18 Multiplier Adder
		DSP Block	9 x 9 Multiplier	18 x 18 Multiplier	27 x 27 Multiplier	Adder Mode	Summed with 36 bit Input
Cyclone V E	A2	25	75	50	25	25	25
	A4	66	198	132	66	66	66
	A5	150	450	300	150	150	150
	A7	156	468	312	156	156	156
	A9	342	1,026	684	342	342	342
Cyclone V	C3	57	171	114	57	57	57
GX	C4	70	210	140	70	70	70
	C5	150	450	300	150	150	150
	C7	156	468	312	156	156	156
	C9	342	1,026	684	342	342	342
Cyclone V GT	D5	150	450	300	150	150	150
	D7	156	468	312	156	156	156
	D9	342	1,026	684	342	342	342
Cyclone V SE	A2	36	108	72	36	36	36
	A4	84	252	168	84	84	84
	A5	87	261	174	87	87	87
	A6	112	336	224	112	112	112
Cyclone V SX	C2	36	108	72	36	36	36
	C4	84	252	168	84	84	84
	C5	87	261	174	87	87	87
							continued



PLL Features

The PLLs in the Cyclone V devices support the following features:

- Frequency synthesis
- On-chip clock deskew
- Jitter attenuation
- Programmable output clock duty cycles
- PLL cascading
- Reference clock switchover
- Programmable bandwidth
- User-mode reconfiguration of PLLs
- Low power mode for each fractional PLL
- Dynamic phase shift
- Direct, source synchronous, zero delay buffer, external feedback, and LVDS compensation modes

Fractional PLL

In addition to integer PLLs, the Cyclone V devices use a fractional PLL architecture. The devices have up to eight PLLs, each with nine output counters. You can use the output counters to reduce PLL usage in two ways:

- Reduce the number of oscillators that are required on your board by using fractional PLLs
- Reduce the number of clock pins that are used in the device by synthesizing multiple clock frequencies from a single reference clock source

If you use the fractional PLL mode, you can use the PLLs for precision fractional-N frequency synthesis—removing the need for off-chip reference clock sources in your design.

The transceiver fractional PLLs that are not used by the transceiver I/Os can be used as general purpose fractional PLLs by the FPGA fabric.

FPGA General Purpose I/O

Cyclone V devices offer highly configurable GPIOs. The following list describes the features of the GPIOs:

- Programmable bus hold and weak pull-up
- \bullet LVDS output buffer with programmable differential output voltage (V $_{\text{OD}}$) and programmable pre-emphasis
- ullet On-chip parallel termination (R_T OCT) for all I/O banks with OCT calibration to limit the termination impedance variation
- On-chip dynamic termination that has the ability to swap between series and parallel termination, depending on whether there is read or write on a common bus for signal integrity
- Easy timing closure support using the hard read FIFO in the input register path, and delay-locked loop (DLL) delay chain with fine and coarse architecture



External Memory Performance

Table 20. External Memory Interface Performance in Cyclone V Devices

The maximum and minimum operating frequencies depend on the memory interface standards and the supported delay-locked loop (DLL) frequency listed in the device datasheet.

Interface	Voltage	Maximum Fre	Minimum Frequency	
	(V)	Hard Controller	Soft Controller	(MHz)
DDR3 SDRAM	1.5	400	303	303
	1.35	400	303	303
DDR2 SDRAM	1.8	400	300	167
LPDDR2 SDRAM	1.2	333	300	167

Related Information

External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Intel's External Memory Interface Spec Estimator tool.

HPS External Memory Performance

Table 21. HPS External Memory Interface Performance

The hard processor system (HPS) is available in Cyclone V SoC devices only.

Interface	Voltage (V)	HPS Hard Controller (MHz)
DDR3 SDRAM	1.5	400
	1.35	400
DDR2 SDRAM	1.8	400
LPDDR2 SDRAM	1.2	333

Related Information

External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Intel's External Memory Interface Spec Estimator tool.

Low-Power Serial Transceivers

Cyclone V devices deliver the industry's lowest power 6.144 Gbps transceivers at an estimated 88 mW maximum power consumption per channel. Cyclone V transceivers are designed to be compliant with a wide range of protocols and data rates.

Transceiver Channels

The transceivers are positioned on the left outer edge of the device. The transceiver channels consist of the physical medium attachment (PMA), physical coding sublayer (PCS), and clock networks.



PCS Features

The Cyclone V core logic connects to the PCS through an 8, 10, 16, 20, 32, or 40 bit interface, depending on the transceiver data rate and protocol. Cyclone V devices contain PCS hard IP to support PCIe Gen1 and Gen2, Gbps Ethernet (GbE), Serial RapidIO[®] (SRIO), and Common Public Radio Interface (CPRI).

Most of the standard and proprietary protocols from 614 Mbps to 6.144 Gbps are supported.

Table 23. Transceiver PCS Features for Cyclone V Devices

PCS Support	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature
3-Gbps and 6-Gbps Basic	0.614 to 6.144	 Phase compensation FIFO Byte serializer 8B/10B encoder Transmitter bit-slip 	 Word aligner Deskew FIFO Rate-match FIFO 8B/10B decoder Byte deserializer Byte ordering Receiver phase compensation FIFO
PCIe Gen1 (x1, x2, x4)	2.5 and 5.0	Dedicated PCIe PHY IP core PIPE 2.0 interface to the core logic	Dedicated PCIe PHY IP core PIPE 2.0 interface to the core logic
PCIe Gen2 (x1, x2, x4) ⁽¹²⁾		logic	logic
GbE	1.25	Custom PHY IP core with preset feature GbE transmitter synchronization state machine	Custom PHY IP core with preset feature GbE receiver synchronization state machine
XAUI (13)	3.125	Dedicated XAUI PHY IP core	Dedicated XAUI PHY IP core
HiGig	3.75	XAUI synchronization state machine for bonding four channels	XAUI synchronization state machine for realigning four channels
SRIO 1.3 and 2.1	1.25 to 3.125	Custom PHY IP core with preset feature SRIO version 2.1-compliant x2 and x4 channel bonding	Custom PHY IP core with preset feature SRIO version 2.1-compliant x2 and x4 deskew state machine
SDI, SD/HD, and 3G-SDI	0.27 ⁽¹⁴⁾ , 1.485, and 2.97	Custom PHY IP core with preset feature	Custom PHY IP core with preset feature
JESD204A	0.3125 ⁽¹⁵⁾ to 3.125		
	,		continued

⁽¹²⁾ PCIe Gen2 is supported for Cyclone V GT and ST devices. The PCIe Gen2 x4 support is PCIe-compatible.

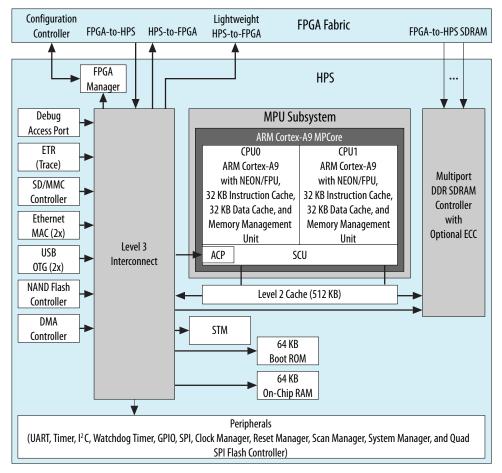
⁽¹³⁾ XAUI is supported through the soft PCS.

 $^{^{(14)}}$ The 0.27-Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.

⁽¹⁵⁾ The 0.3125-Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.



Figure 11. HPS with Dual-Core Arm Cortex-A9 MPCore Processor



System Peripherals and Debug Access Port

Each Ethernet MAC, USB OTG, NAND flash controller, and SD/MMC controller module has an integrated DMA controller. For modules without an integrated DMA controller, an additional DMA controller module provides up to eight channels of high-bandwidth data transfers. Peripherals that communicate off-chip are multiplexed with other peripherals at the HPS pin level. This allows you to choose which peripherals to interface with other devices on your PCB.

The debug access port provides interfaces to industry standard JTAG debug probes and supports Arm CoreSight debug and core traces to facilitate software development.



HPS-FPGA AXI Bridges

The HPS-FPGA bridges, which support the Advanced Microcontroller Bus Architecture (AMBA®) Advanced eXtensible Interface (AXI™) specifications, consist of the following bridges:

- FPGA-to-HPS AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the FPGA fabric to issue transactions to slaves in the HPS.
- HPS-to-FPGA AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the HPS to issue transactions to slaves in the FPGA fabric.
- Lightweight HPS-to-FPGA AXI bridge—a lower latency 32 bit width bus that allows
 the HPS to issue transactions to slaves in the FPGA fabric. This bridge is primarily
 used for control and status register (CSR) accesses to peripherals in the FPGA
 fabric.

The HPS-FPGA AXI bridges allow masters in the FPGA fabric to communicate with slaves in the HPS logic, and vice versa. For example, the HPS-to-FPGA AXI bridge allows you to share memories instantiated in the FPGA fabric with one or both microprocessors in the HPS, while the FPGA-to-HPS AXI bridge allows logic in the FPGA fabric to access the memory and peripherals in the HPS.

Each HPS-FPGA bridge also provides asynchronous clock crossing for data transferred between the FPGA fabric and the HPS.

HPS SDRAM Controller Subsystem

The HPS SDRAM controller subsystem contains a multiport SDRAM controller and DDR PHY that are shared between the FPGA fabric (through the FPGA-to-HPS SDRAM interface), the level 2 (L2) cache, and the level 3 (L3) system interconnect. The FPGA-to-HPS SDRAM interface supports AMBA AXI and Avalon® Memory-Mapped (Avalon-MM) interface standards, and provides up to six individual ports for access by masters implemented in the FPGA fabric.

To maximize memory performance, the SDRAM controller subsystem supports command and data reordering, deficit round-robin arbitration with aging, and high-priority bypass features. The SDRAM controller subsystem supports DDR2, DDR3, or LPDDR2 devices up to 4 Gb in density operating at up to 400 MHz (800 Mbps data rate).

FPGA Configuration and Processor Booting

The FPGA fabric and HPS in the SoC are powered independently. You can reduce the clock frequencies or gate the clocks to reduce dynamic power, or shut down the entire FPGA fabric to reduce total system power.

You can configure the FPGA fabric and boot the HPS independently, in any order, providing you with more design flexibility:

- You can boot the HPS independently. After the HPS is running, the HPS can fully or
 partially reconfigure the FPGA fabric at any time under software control. The HPS
 can also configure other FPGAs on the board through the FPGA configuration
 controller.
- You can power up both the HPS and the FPGA fabric together, configure the FPGA fabric first, and then boot the HPS from memory accessible to the FPGA fabric.



Apart from lowering cost and power consumption, partial reconfiguration increases the effective logic density of the device because placing device functions that do not operate simultaneously is not necessary. Instead, you can store these functions in external memory and load them whenever the functions are required. This capability reduces the size of the device because it allows multiple applications on a single device—saving the board space and reducing the power consumption.

Intel simplifies the time-intensive task of partial reconfiguration by building this capability on top of the proven incremental compile and design flow in the Intel Quartus Prime design software. With the Intel solution, you do not need to know all the intricate device architecture details to perform a partial reconfiguration.

Partial reconfiguration is supported through the FPP x16 configuration interface. You can seamlessly use partial reconfiguration in tandem with dynamic reconfiguration to enable simultaneous partial reconfiguration of both the device core and transceivers.

Enhanced Configuration and Configuration via Protocol

Cyclone V devices support $1.8\ V$, $2.5\ V$, $3.0\ V$, and $3.3\ V$ programming voltages and several configuration schemes.

Table 24. Configuration Schemes and Features Supported by Cyclone V Devices

Mode	Data Width	Max Clock Rate (MHz)	Max Data Rate (Mbps)	Decompressi on	Design Security	Partial Reconfigurat ion ⁽¹⁸⁾	Remote System Update
AS through the EPCS and EPCQ serial configuration device	1 bit, 4 bits	100	_	Yes	Yes	_	Yes
PS through CPLD or external microcontroller	1 bit	125	125	Yes	Yes	_	_
FPP	8 bits	125	_	Yes	Yes	_	Parallel flash
	16 bits	125	_	Yes	Yes	Yes	loader
CvP (PCIe)	x1, x2, and x4 lanes	_	_	Yes	Yes	Yes	_
JTAG	1 bit	33	33	_	_	_	_

Instead of using an external flash or ROM, you can configure the Cyclone V devices through PCIe using CvP. The CvP mode offers the fastest configuration rate and flexibility with the easy-to-use PCIe hard IP block interface. The Cyclone V CvP implementation conforms to the PCIe 100 ms power-up-to-active time requirement.

Related Information

Configuration via Protocol (CvP) Implementation in Intel FPGAs User Guide Provides more information about CvP.

⁽¹⁸⁾ The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.



Date	Version	Changes
July 2014	2014.07.07	Updated the I/O vertical migration figure to clarify the migration capability of Cyclone V SE and SX devices.
December 2013	2013.12.26	 Cyclone V SE and SX devices. Corrected single or dual-core ARM Cortex-A9 MPCore processor-up to 925 MHz from 800 MHz. Removed "Preliminary" texts from Ordering Code figures, Maximum Resources, Package Plan and I/O Vertical Migration tables. Removed the note "The number of GPIOs does not include transceiver I/Os. In the Quartus II software, the number of user I/Os includes transceiver I/Os." for GPIOs in the Maximum Resource Counts table for Cyclone V E and SE. Added link to Altera Product Selector for each device variant. Updated Embedded Hard IPs for Cyclone V GT devices to indicate Maximum 2 hard PCIe and 2 hard memory controllers. Added leaded package options. Removed the note "The number of PLLs includes general-purpose fractional PLLs and transceiver fractional PLLs." for all PLLs in the Maximum Resource Counts table. Corrected max LVDS counts for transmitter and receiver for Cyclone V E A5 device from 84 to 60. Corrected max LVDS counts for transmitter and receiver for Cyclone V E A9 device from 140 to 120. Corrected variable-precision DSP block, 27 x 27 multiplier, 18 x 18 multiplier adder mode and 18 x 18 multiplier adder summed with 36 bit input for Cyclone V SE devices from 58 to 84. Corrected 18 x 18 multiplier for Cyclone V SE devices from 116 to 168. Corrected LVDS transmitter for Cyclone V SE A2 and A4 as well as SX C2 and C4 devices from 31 to 32. Corrected LVDS receiver for Cyclone V SE A2 and A4 as well as SX C2 and C4 devices from 35 to 37. Corrected transceiver speed grade for Cyclone V ST devices ordering code from 4 to 5. Updated the DDR3 SDRAM for the maximum frequency's soft controller and the minimum frequency from 300 to 303 for voltage 1.35v. Added links to Altera's External Memory Spec Estimator tool to the topics
		 listing the external memory interface performance. Corrected XAUI is supported through the soft PCS in the PCS features for Cyclone V.
		Added decompression support for the CvP configuration mode.
May 2013	2013.05.06	 Added link to the known document issues in the Knowledge Base. Moved all links to the Related Information section of respective topics for easy reference.
		Corrected the title to the PCIe hard IP topic. Cyclone V devices support only PCIe Gen1 and Gen2. Undeted Supporting Feature in Table 1 of Increased handwidth capacity to
		 Updated Supporting Feature in Table 1 of Increased bandwidth capacity to '6.144 Gbps'. Updated Description in Table 2 of Low-power high-speed serial interface to
		'6.144 Gbps'.
		 Updated Description in Table 3 of Cyclone V GT to '6.144 Gbps'. Updated the M386 package to M383 for Figure 1, Figure 2 and Figure 3.
		 Updated Figure 2 and Figure 3 for Transceiver Count by adding 'F: 4'.
		Updated LVDS in the Maximum Resource Counts tables to include Transmitter and Receiver values.
		 Updated the package plan with M383 for the Cyclone V E device.
		 Removed the M301 and M383 packages from the Cyclone V GX C4 device. Updated the GPIO count to '129' for the M301 package of the Cyclone V GX C5 device.
		Updated 5 Gbps to '6.144 Gbps' forCyclone V GT device.
	_1	continued